HALOGEN FREE



Vishay Siliconix

N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	Q _g (Typ.)			
30	0.024 at V _{GS} = 10 V	10.9	3.8 nC			
30	0.030 at V _{GS} = 4.5 V	9.7	3.0 110			

		SO-8		
S 2 S 3 G 4	=		8 7 6 5	D D D
		Top View		

Ordering Information: Si4128DY-T1-E3 (Lead (Pb)-free)

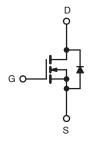
Si4128DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET® Power MOSFET
- 100 % R_g Tested

APPLICATIONS

- Notebook PC
 - System Power
 - Load Switch



N-Channel MOSFET

ABSOLUTE MAXIMUM RATIN	I GS T _A = 25 °C,	unless other	wise noted		
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V_{DS}	30	V		
Gate-Source Voltage		V_{GS}	± 20	V	
	T _C = 25 °C		10.9		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	i .	8.7		
Continuous Brain Current (1) = 130 C)	T _A = 25 °C	l o	7.5 ^{b, c}		
	T _A = 70 °C	1 -	6 ^{b, c}	Α	
Pulsed Drain Current		I _{DM}	30		
Continuous Source-Drain Diode Current	T _C = 25 °C	l _a	4.2		
Continuous Source-Drain Diode Current	T _A = 25 °C	l _S	2 ^{b, c}		
	T _C = 25 °C		5		
Maximum Dayyar Dissination	T _C = 70 °C	P _D	3.2	w	
Maximum Power Dissipation	T _A = 25 °C		2.4 ^{b, c}	VV	
	T _A = 70 °C	1	1.5 ^{b, c}		
Operating Junction and Storage Temperature	T _J , T _{sta}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R_{thJA}	42	53	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	19	25	J 5/ VV	

Notes:

- a. $T_C = 25$ °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. Maximum under Steady State conditions is 85 $^{\circ}$ C/W.

Si4128DY

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SPECIFICATIONS $T_J = 25$ °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			٧	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		35		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	10 – 230 μΛ		- 4.5			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	1.0		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zara Cata Valtaga Drain Current	1	V _{DS} = 30 V, V _{GS} = 0 V	: 0 V		1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			5	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	20			Α	
	Б	$V_{GS} = 10 \text{ V}, I_D = 7.8 \text{ A}$		0.020	0.024		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 7.0 \text{ A}$		0.024	0.030	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 7.8 A		17		S	
Dynamic ^b				<u>I</u>		1	
Input Capacitance	C _{iss}			435			
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		95		pF	
Reverse Transfer Capacitance	C _{rss}			42			
Total Oata Observe	0	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 7.8 A		8	12	nC	
Total Gate Charge	Q _g			3.8	6		
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 7.8 \text{ A}$		1.4			
Gate-Drain Charge	Q_{gd}			1.1			
Gate Resistance	R_{g}	f = 1 MHz	1.5	3.2	4.5	Ω	
Turn-On Delay Time	t _{d(on)}			15	25		
Rise Time	t _r	V_{DD} = 15 V, R_L = 2.4 Ω		12	20	1	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 6.3$ A, V_{GEN} = 4.5 V, R_g = 1 Ω		13	20	1	
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			5	10	ns	
Rise Time	t _r	V_{DD} = 15 V, R_L = 2.4 Ω		10	15		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 6.3~A,~V_{GEN}$ = 10 V, R_g = 1 Ω		15	25		
Fall Time	t _f			10	15		
Drain-Source Body Diode Characteristi	cs			<u>I</u>			
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			4.2		
Pulse Diode Forward Current	I _{SM}				30	A	
Body Diode Voltage	V _{SD}	$I_S = 6.3 \text{ A}, V_{GS} = 0 \text{ V}$		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			15	25	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	L 60 A dl/dt 100 A/: T 65 00		7	12	nC	
Reverse Recovery Fall Time	t _a	$I_F = 6.3 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		9			
Reverse Recovery Rise Time	t _b			6		ns	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

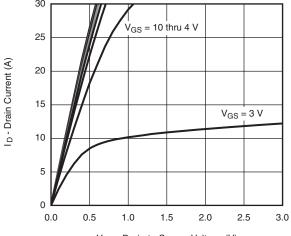
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %

b. Guaranteed by design, not subject to production testing.

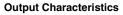


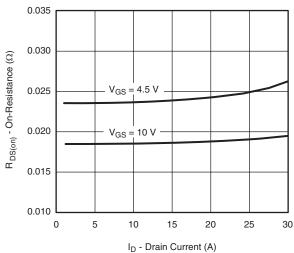
Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

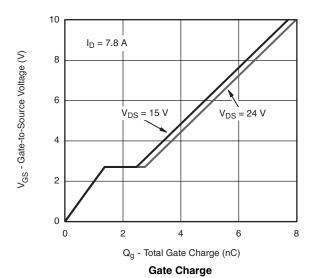


V_{DS} - Drain-to-Source Voltage (V)





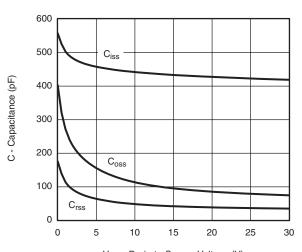
On-Resistance vs. Drain Current



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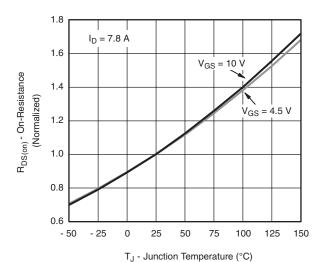
V_{GS} - Gate-to-Source Voltage (V)





V_{DS} - Drain-to-Source Voltage (V)

Capacitance



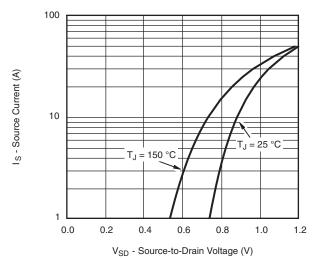
On-Resistance vs. Junction Temperature

Si4128DY

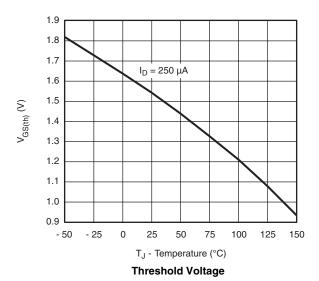
Vishay Siliconix

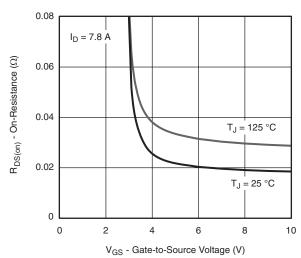
VISHAY.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

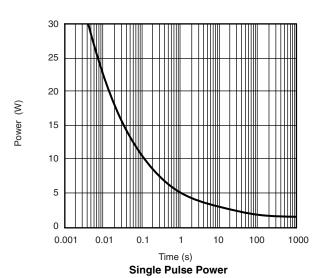


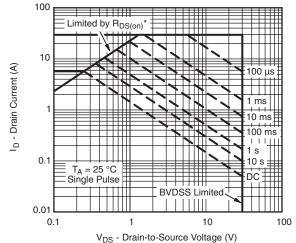
Source-Drain Diode Forward Voltage





On-Resistance vs. Gate-to-Source Voltage





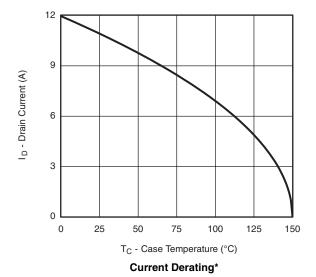
* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

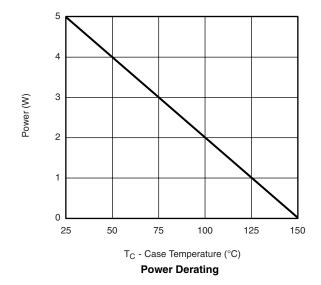
Safe Operating Area, Junction-to-Ambient



Si4128DY Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



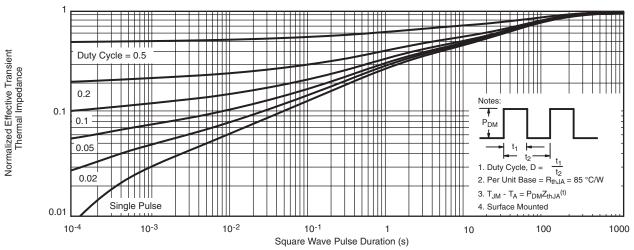


^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

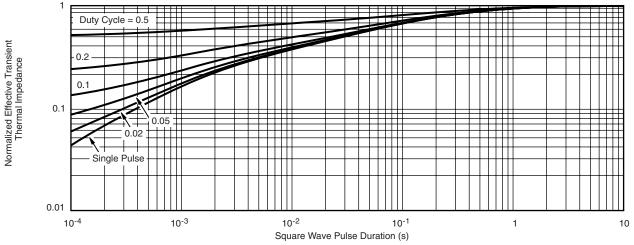
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?69004.



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	IETERS	INCHES			
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050	0.050 BSC		
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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